

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Kyu Jin PARK	06/17/2011
Jae Hoon CHUNG	06/24/2011
Han Kyu CHO	06/24/2011
Yeong Hyeon KWON	10/19/2011
Sung Ho MOON	10/19/2011
RECEIVING PARTY DATA	
Name:	LG ELECTRONICS INC.
Street Address:	20, Yeouido-dong, Yeongdeungpo-gu
City:	Seoul
State/Country:	REPUBLIC OF KOREA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13142266
CORRESPONDENCE DATA	
Fax Number:	(213)623-2211
Phone:	213-623-2221
Email:	patent@hlaw.com
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Correspondent Name:	LEE, HONG, DEGERMAN, KANG & WAIMEY
Address Line 1:	660 S. FIGUEROA STREET
Address Line 2:	Suite 2300
Address Line 4:	LOS ANGELES, CALIFORNIA 90017
ATTORNEY DOCKET NUMBER:	2101-5000
NAME OF SUBMITTER:	Harry S. Lee
Total Attachments: 2 source=3_2101-5000_Assignment#page1.tif source=3_2101-5000_Assignment#page2.tif	

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PATENT
REEL: 027095 FRAME: 0229

ASSIGNMENT

(1-8) *Insert Name(s) of Inventor(s)*

(1) Kyu Jin PARK

(5) Sung Ho MOON

(2) Jae Hoon CHUNG

(6)

(3) Han Kyu CHO

(7)

(4) Yeong Hyeon KWON

(8)

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(9) *Insert name of Assignee*

(9) LG Electronics Inc.

(10) *Insert state of Incorporation of Assignee*

(10) Republic of Korea

(11) *Insert address of Assignee*

(11) 20, Yeouido-dong, Yeongdeungpo-gu, Seoul, 150-721, Republic of Korea

(hereinafter designated as the Assignee) the entire worldwide right, title and interest in the invention known as

(12) *Insert identification of Invention, such as Title, Case Number or Foreign Application Number*

(12) **METHOD OF ALLOCATING RESOURCE FOR RELAY (Application No.: 13/142,266)**

for which the undersigned has (have) executed an application for patent in the United States of America and all patent applications in foreign countries corresponding thereto or based thereon.

1) The undersigned agree(s) to execute all papers necessary in connection with any original, reissue, divisional and continuing United States and foreign applications for the above-identified invention and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed any agreement in conflict herewith.

The undersigned hereby appoints **the Attorneys associated with Customer No. 035884** the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

PATENT

REEL: 027095 FRAME: 0230

Date: June 11, 2011

Signature of Inventor (1)

Date: June 24th, 2011

Signature of Inventor (2)

Date: June 24, 2011

Signature of Inventor (3)

Date: Oct 19th, 2011

Signature of Inventor (4)

Date: Oct. 19th, 2011

Signature of Inventor (5)